

Status of upgrade of CN

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Outline

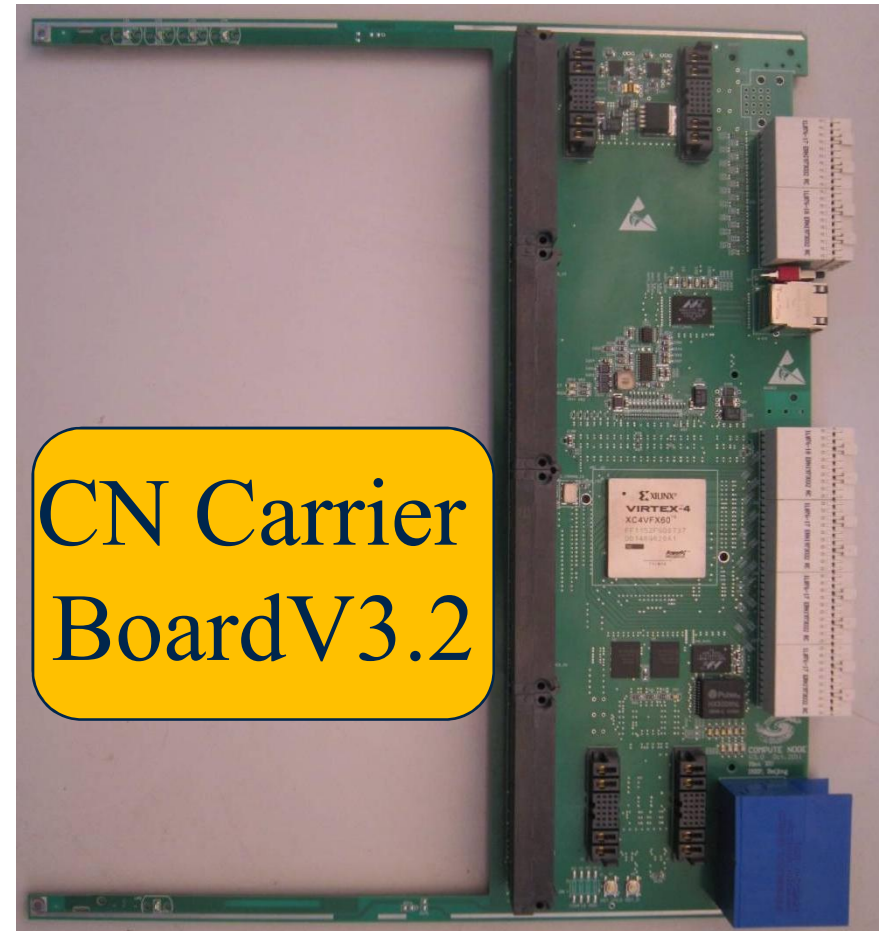


- # Status of CN Carrier Board
- # Status of RTM cards
- # Status of CN Power Module
- # Summary

Status of CN Carrier Board



- # Version V3.2 for Carrier Board
- # DDR2, Flash, GbE, UART all works well.
- # CPLD programming works well with four xFP cards.
- # But if one or more xFP cards uninstalled, CPLD programming not well.
- # New version V3.3 is upgraded.



Upgrade in CN V3.3



- # 1, Flash Array resistor changed to single resistor, avoid soldering problem.
- # 2, Double MGT power supply current.
 - VTT_MGT_1V5 and AVCCAUXMGT_1V2.
- # 3, Add a line between a CPLD pin(P22) and the carrier flash WEN pins.
- # 3.1 Add new two lines IPMI bus to FPGA0, used J7-1/2 with weak pull up.
- # 4, U1 chip ADG3233BRM power supply changed
 - from VCC3.3C_AMC_MP to VCC3.3V.
- # 5, Swapped 4 pair of LVDS P/N connection on CN carrier FPGA side.
 - A4_TP/N2, A4_TP/N5, A4_TP/N4, A4_RP/N3
- # 6, Remove RJ45 and add a 2x10 connector.
- # 7, An RTM IO board is new designed for cable convenient connection.
 - JTAG, UART and RJ45

CN_V3.3



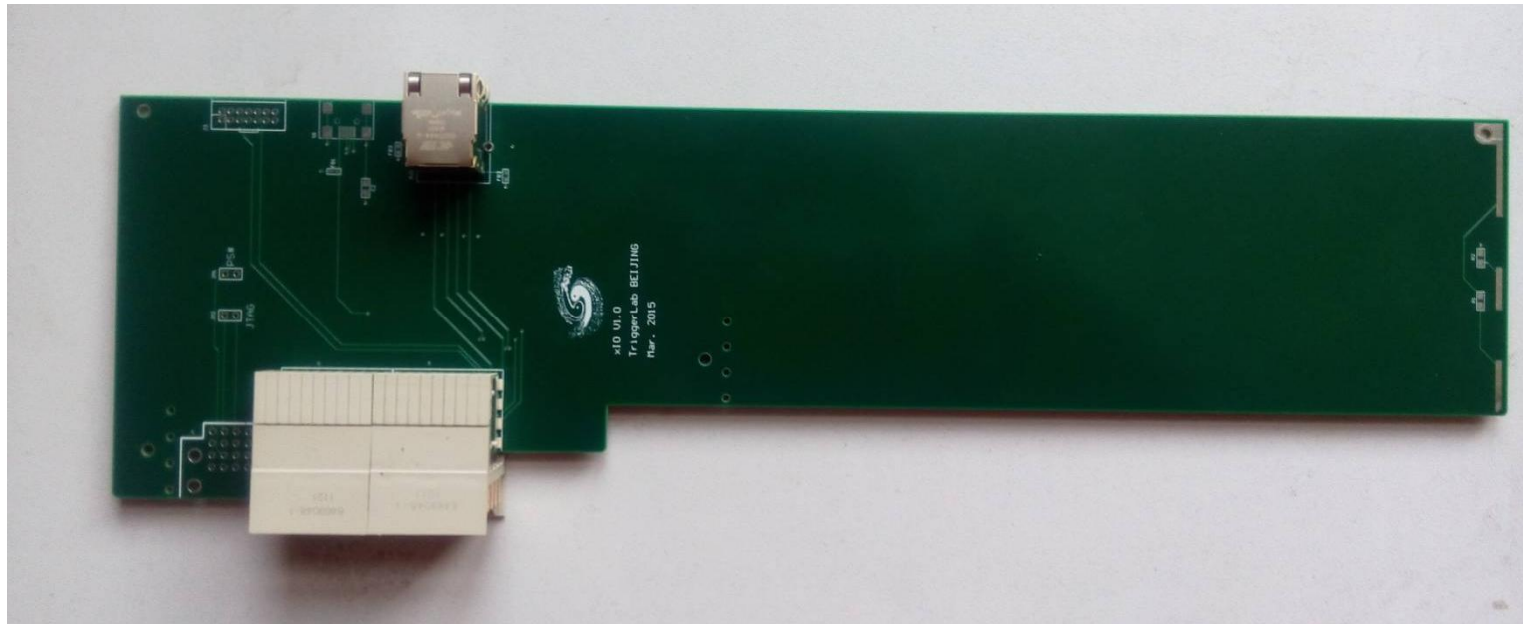
- # Received the new versions CNV3.3 cards yesterday(05/11).
- # 4 boards are produced.
- # 2 of CN_V3.3 will be taken to Giessen for testing.
- # Testing will started in IHEP and Giessen.



RTM cards



- # Backplane connectors has been installed.
- # RJ45, JTAG and UART has to be soldered by hand in Lab.
- # 4 RTM cards will be produced.
- # Try to finished this week. Then 2 of RTMs can be taken to Giessen with CN_V3.3 together.



Status of CN Power Module



- # Now V1.2 works well.
- # New version is needed to meet CN_V3.3 upgrade.
- # Two IPMI-L buses will be on V1.3.
 - One is for CN on board sensor connection, called IPMI Sensor Bus.
 - The other one is for xFP MMCs connection, called IPMI-L Bus
- # PCB layout is going on.

Summary



- # CN_V3.3 is finished, Testing will be held both in Giessen and Beijing.
- # PCB of RTM is finished, Soldering working will be finished this week.
- # New version of CN Power Module is needed. Design work is going on.